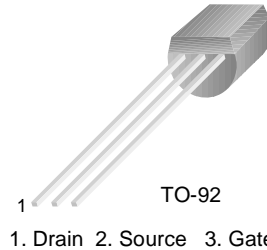


# PF5102

## N-Channel Switch

- This device is designed for low level analog switching, sample and hold circuits and chopper stabized amplifiers.
- Sourced from process 51.
- See J111 for characteristics.



## Absolute Maximum Ratings \* $T_A=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Units
$V_{DG}$	Drain-Gate Voltage	40	V
$V_{GS}$	Gate-Source Voltage	-40	V
$I_{GF}$	Forward Gate Current	50	A
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 ~ +150	$^\circ\text{C}$

\* These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

### NOTES:

1. These ratings are based on a maximum junction temperature of 150 degrees C.
2. These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

## Electrical Characteristics $T_A=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Max.	Units
<b>Off Characteristics</b>					
$V_{(BR)GSS}$	Gate-Source Breakdwon Voltage	$I_C = -1.0\mu\text{A}, V_{DS} = 0$	-40		V
$I_{GSS}$	Gate Reverse Current	$V_{GS} = -15\text{V}, V_{DS} = 0$ $V_{GS} = -15\text{V}, V_{DS} = 0, T_A = 125^\circ\text{C}$		-1.0 -0.2	
		$G = 1.0\text{mA}, V_{DS} = 0$		1.0	
<b>On Characteristics</b>					
$I_{DSS}$	Zero-Gate Voltage Drain Current *	$V_{DS} = 15\text{V}, V_{GS} = 0$	4.0	20	nA
<b>Small Signal Characteristics</b>					
$g_{fs}$	Forward Transfer Conductance	$V_{DS} = 15\text{V}, V_{GS} = 0, f = 1.0\text{KHz}$	11,000		$\mu\text{mhos}$
$g_{oss}$	Output Conductance	$V_{DS} = 15\text{V}, I_D = 500\mu\text{A}, f = 1.0\text{KHz}$		25	$\mu\text{mhos}$
$C_{iss}$	Input Capacitance	$V_{DG} = 15\text{V}, V_{GS} = 0, f = 1.0\text{MHz}$		16	pF
$C_{rss}$	Reverse Transfer Capacitance	$V_{DG} = 15\text{V}, V_{GS} = 0, f = 1.0\text{MHz}$		6	pF

\* Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 1.0\%$

## Thermal Characteristics $T_A=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Max.	Units
$P_D$	Total Device Dissipation Derate above $25^\circ\text{C}$	625 5.0	mW mW/ $^\circ\text{C}$
$R_{\theta JC}$	Thermal Resistance, Junction to Case	125	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	357	$^\circ\text{C/W}$

# Package Dimensions

## TO-92



Dimensions in Millimeters

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